

## Features

- Trench Power LV MOSFET Technology
- Moisture Sensitivity Level 3
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

## Maximum Ratings

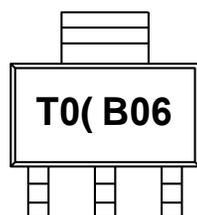
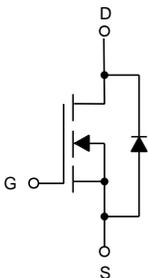
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 64°C/W Junction to Ambient(Steady-State)<sup>(Note2)</sup>

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current	$T_a=25^\circ\text{C}$	4	A
	$T_a=100^\circ\text{C}$	2.5	
Pulsed Drain Current <sup>(Note3)</sup>	$I_{DM}$	16	A
Single Pulsed Avalanche Energy <sup>(Note4)</sup>	$P_D$	2	W

Note:

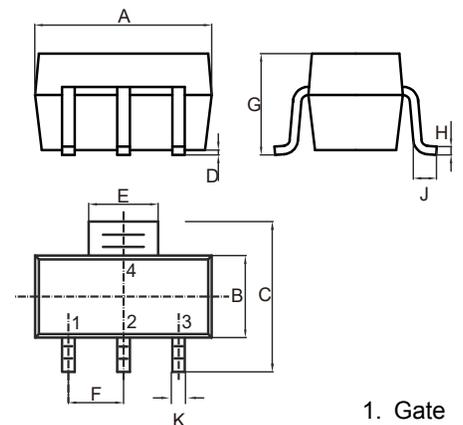
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ\text{C}$ .
3. Repetitive rating; pulse width limited by max. junction temperature.
4.  $P_D$  is based on max. junction temperature, using junction to ambient thermal resistance.

## Internal Structure and Marking Code



# N-Channel Power MOSFET

## SOT-223



1. Gate
- 2,4. Drain
3. Source

DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	0.248	0.264	6.30	6.70	
B	0.130	0.146	3.30	3.70	
C	0.264	0.287	6.70	7.30	
D	0.001	0.004	0.02	0.10	
E	0.114	0.122	2.90	3.10	
F	0.091		2.30		TYP.
G	---	0.071	---	1.80	
H	0.009	0.014	0.23	0.35	
J	0.030	---	0.75	---	
K	0.026	0.033	0.66	0.84	

**Electrical Characteristics @ 25°C (Unless Otherwise Specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$			1	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.9	1.4	2	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=4A$		68	88	m $\Omega$
		$V_{GS}=4.5V, I_D=3A$		74	96	
Gate Resistance	$R_g$	F=1 MHz, Open drain		2.2		$\Omega$
<b>Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$				4	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=2A$			1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F=2A, di_F/dt=100A/\mu s$		21		ns
Reverse Recovery Charge	$Q_{rr}$			12		nC
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, f=1MHz$		501		pF
Output Capacitance	$C_{oss}$			26		
Reverse Transfer Capacitance	$C_{rss}$			21		
Total Gate Charge	$Q_g$	$V_{DS}=30V, V_{GS}=10V, I_D=2A$		10.4		nC
Gate-Source Charge	$Q_{gs}$			1.3		
Gate-Drain Charge	$Q_{gd}$			2.4		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=30V, R_G=2.2\Omega$ $I_D=2A, V_{GS}=10V$		2.3		ns
Turn-On Rise Time	$t_r$			13.4		
Turn-Off Delay Time	$t_{d(off)}$			15.6		
Turn-Off Fall Time	$t_f$			1.7		

**Curve Characteristics**

Fig. 1 - Typical Output Characteristics

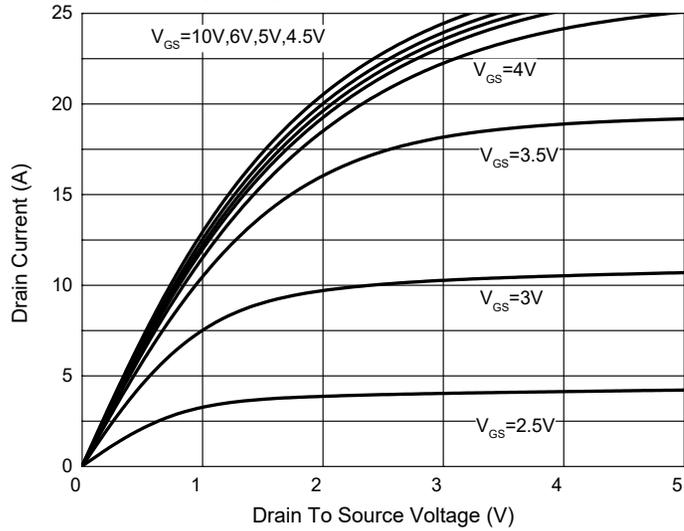


Fig. 2 - Transfer Characteristics

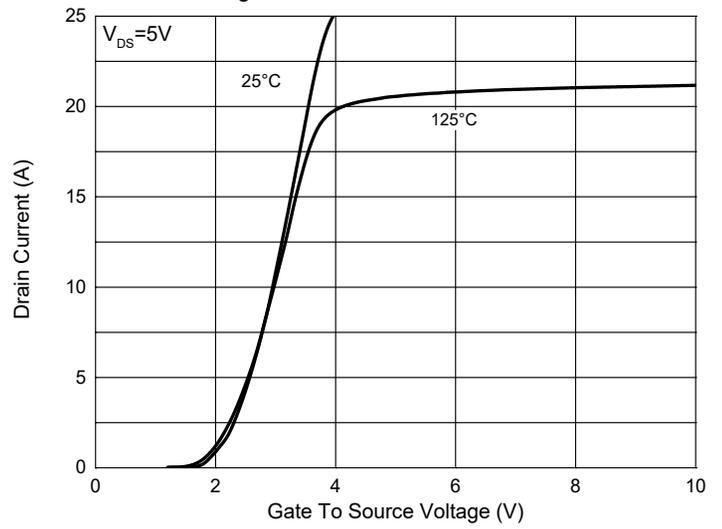


Fig. 3 -  $R_{DS(ON)} - V_{GS}$

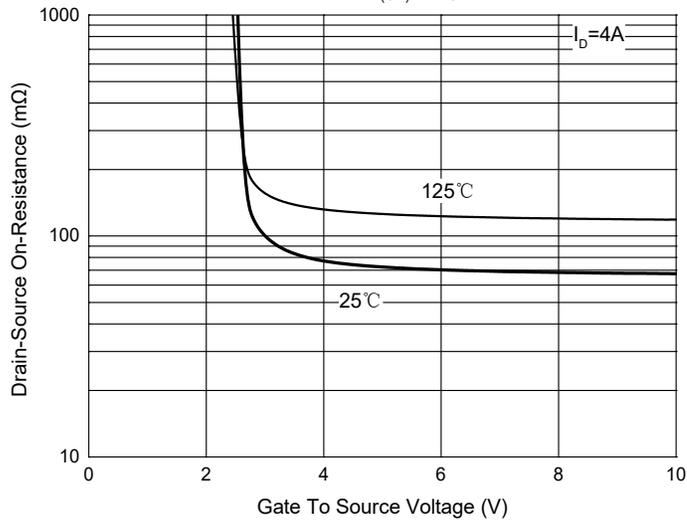


Fig. 4 -  $R_{DS(ON)} - I_D$

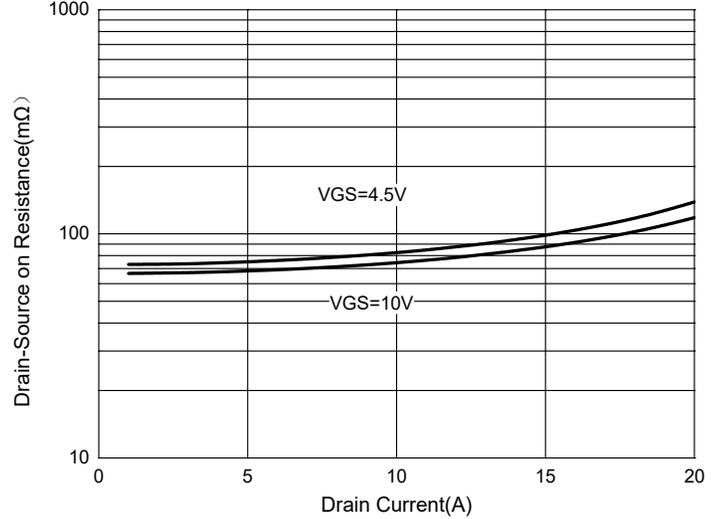


Fig. 5 - Capacitance Characteristics

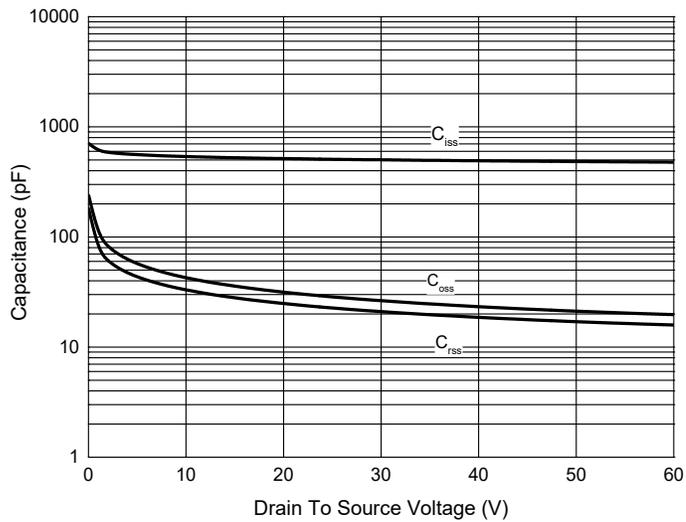
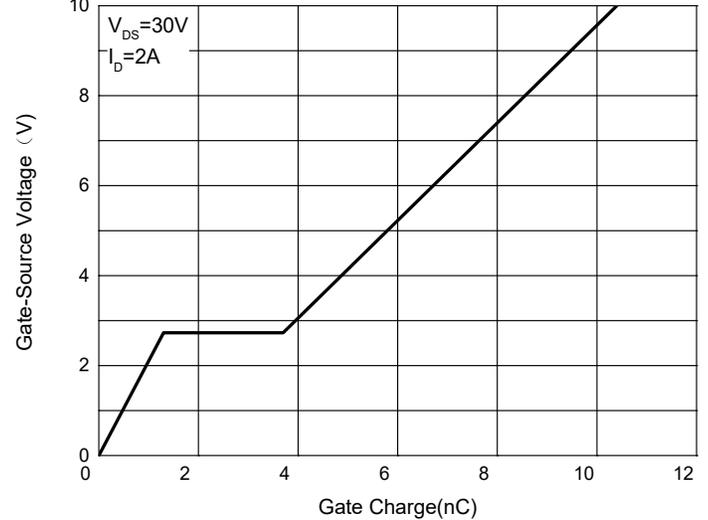


Fig. 6 - Gate Charge



**Curve Characteristics**

Fig. 7 - Normalized Threshold Voltage

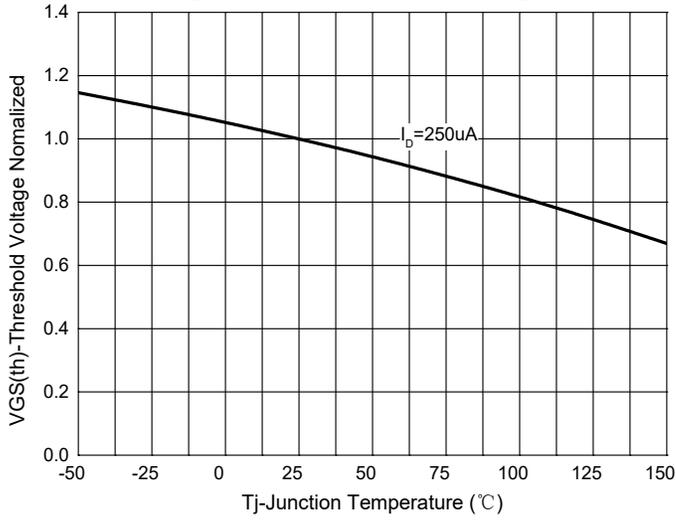


Fig.8-Normalized On Resistance Characteristics

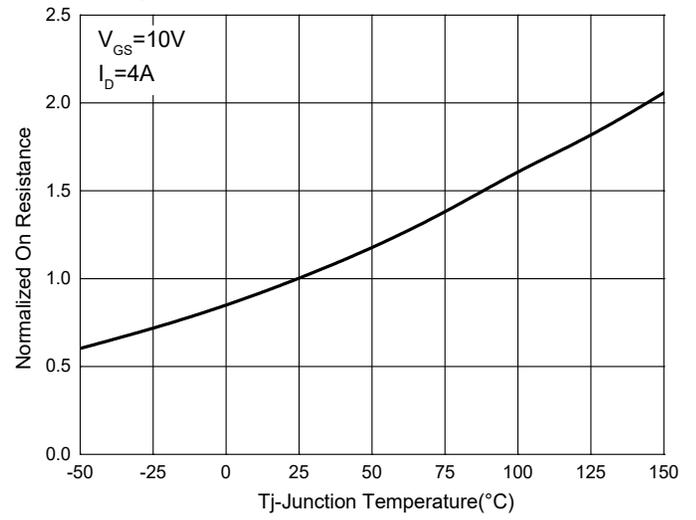


Fig.9 - I<sub>s</sub>—V<sub>SD</sub>

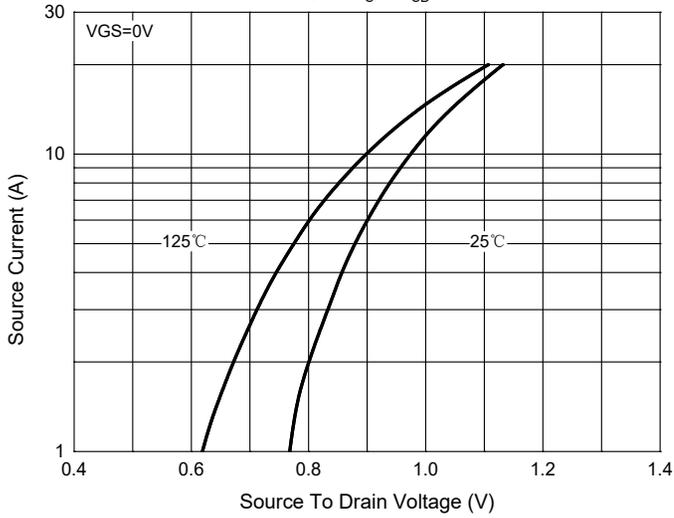


Fig. 10 - Drain Current

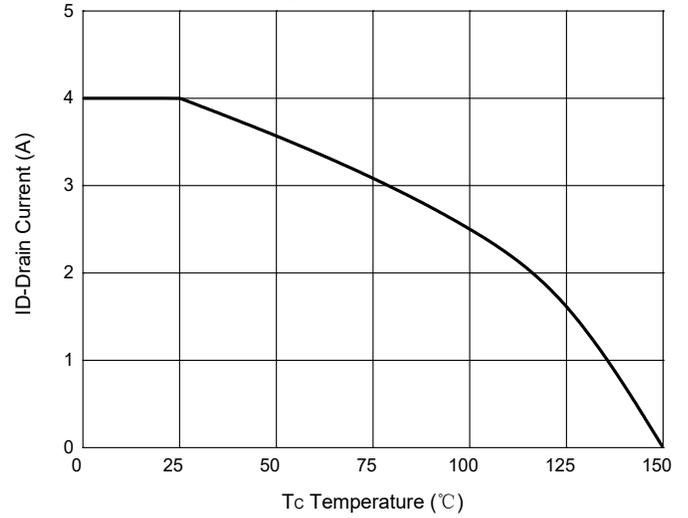
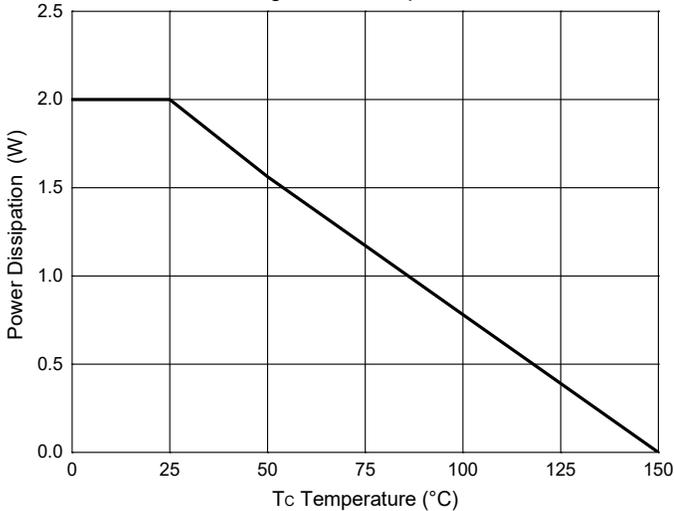


Fig.11-PD Dissipation



**Curve Characteristics**

Fig. 12 - Safe Operation Area

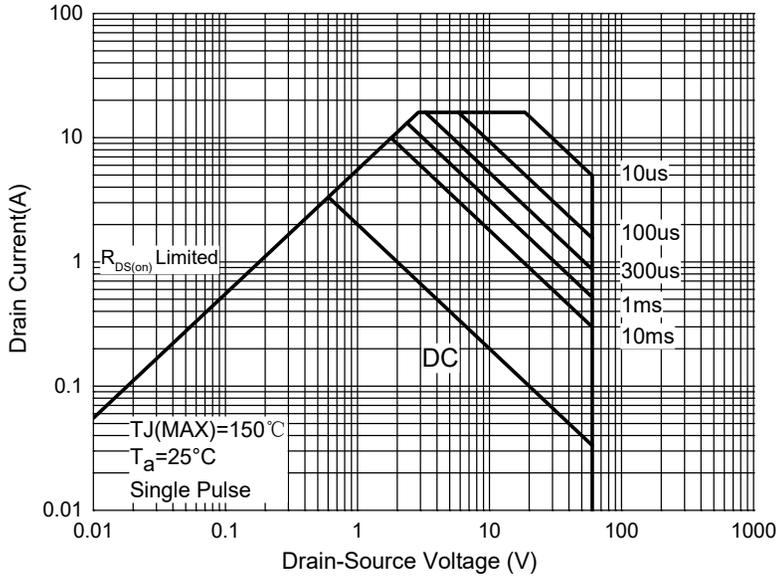
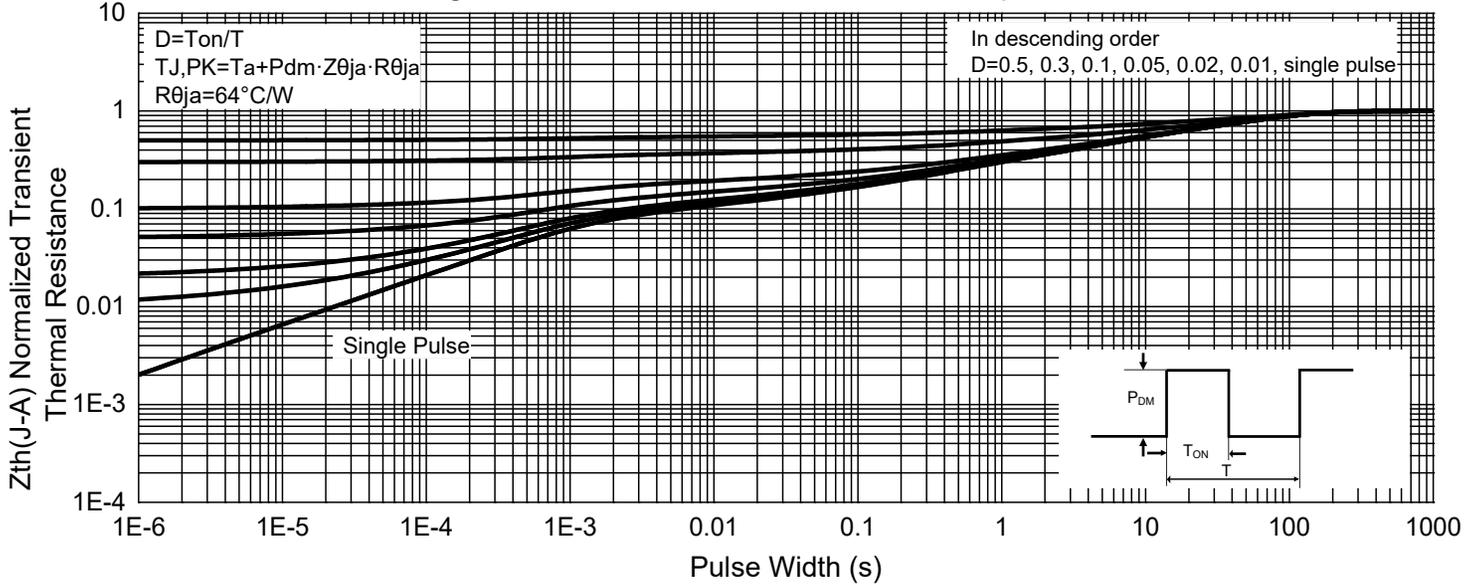


Fig. 13 - Normalized Transient Thermal Impedance



## Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 2.5Kpcs/Reel

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